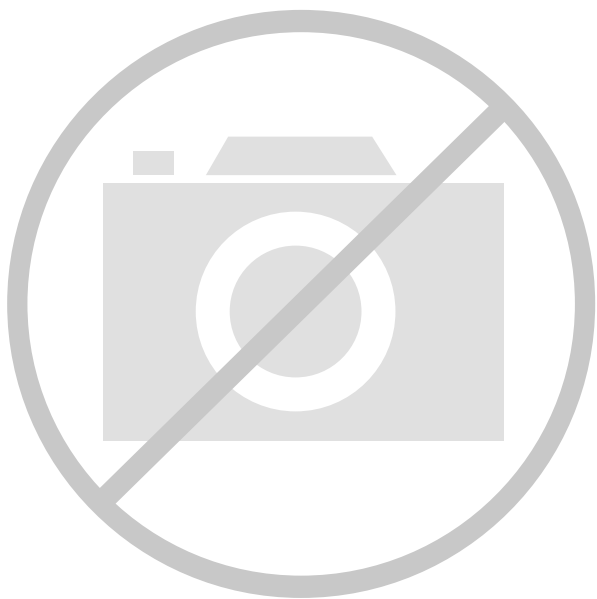




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2016
Number of Logic Elements/Cells	-
Total RAM Bits	18432
Number of I/O	138
Number of Gates	125000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	256-LBGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax125-fgg256i

Up to four individual signals can be brought out to dedicated probe pins (PRA/B/C/D) on the device. The probe circuitry is accessed and controlled via Silicon Explorer II, Microsemi's integrated verification and logic analysis tool that attaches to the serial port of a PC and communicates with the FPGA via the JTAG port (See "Silicon Explorer II Probe Interface" on page 2-109).

Summary

Microsemi's Axcelerator family of FPGAs extends the successful SX-A architecture, adding embedded RAM/FIFOs, PLLs, and high-speed I/Os. With the support of a suite of robust software tools, design engineers can incorporate high gate counts and fixed pins into an Axcelerator design yet still achieve high performance and efficient device utilization.

Related Documents

Application Notes

Simultaneous Switching Noise and Signal Integrity

http://www.microsemi.com/soc/documents/SSN_AN.pdf

Axcelerator Family PLL and Clock Management

http://www.microsemi.com/soc/documents/AX_PLL_AN.pdf

Implementation of Security in Actel Antifuse FPGAs

http://www.microsemi.com/soc/documents/Antifuse_Security_AN.pdf

User's Guides and Manuals

Antifuse Macro Library Guide

http://www.microsemi.com/soc/documents/libguide_UG.pdf

SmartGen, FlashROM, Analog System Builder, and Flash Memory System Builder

http://www.microsemi.com/soc/documents/genguide_ug.pdf

Silicon Sculptor II User's Guide

http://www.microsemi.com/soc/documents/silisculptII_sculpt3_ug.pdf

White Paper

Design Security in Nonvolatile Flash and Antifuse FPGAs

http://www.microsemi.com/soc/documents/DesignSecurity_WP.pdf

Understanding Actel Antifuse Device Security

http://www.microsemi.com/soc/documents/DesignSecurity_WP.pdf

Miscellaneous

Libero IDE flow diagram

<http://www.microsemi.com/soc/products/tools/libero/flow.html>

I/O Module Timing Characteristics

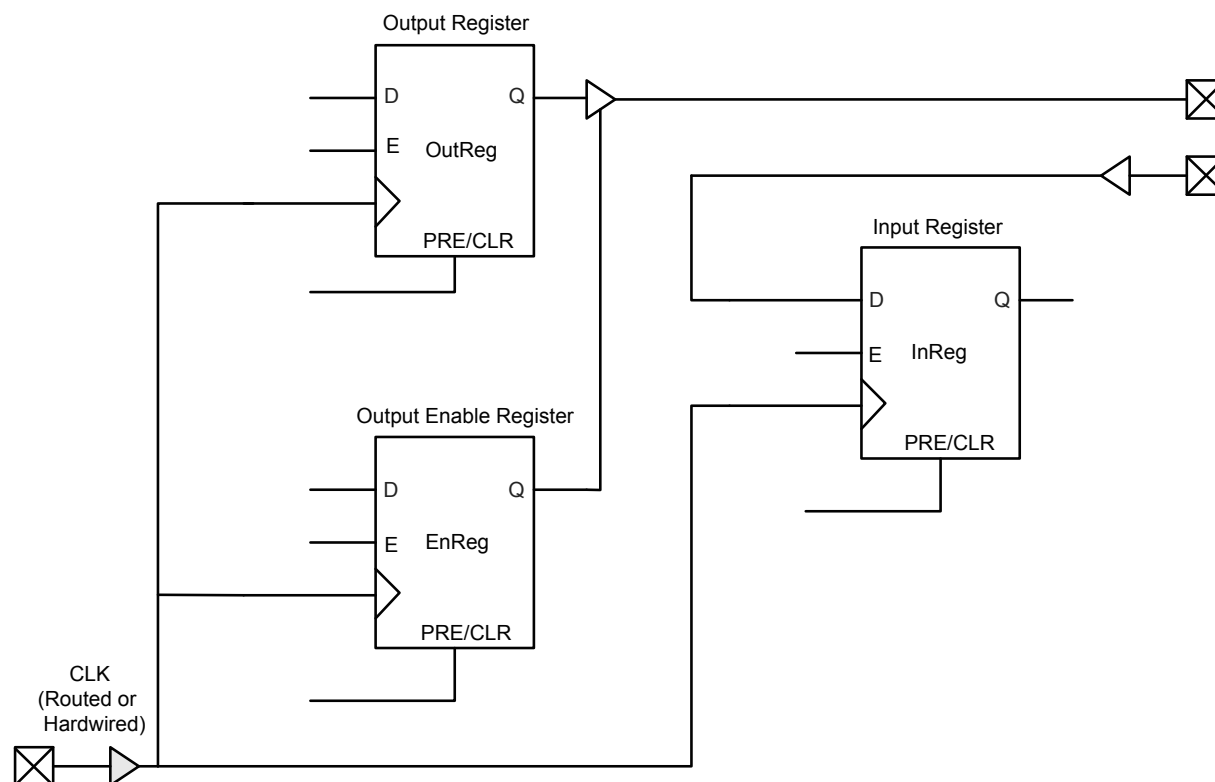


Figure 2-11 • Timing Model

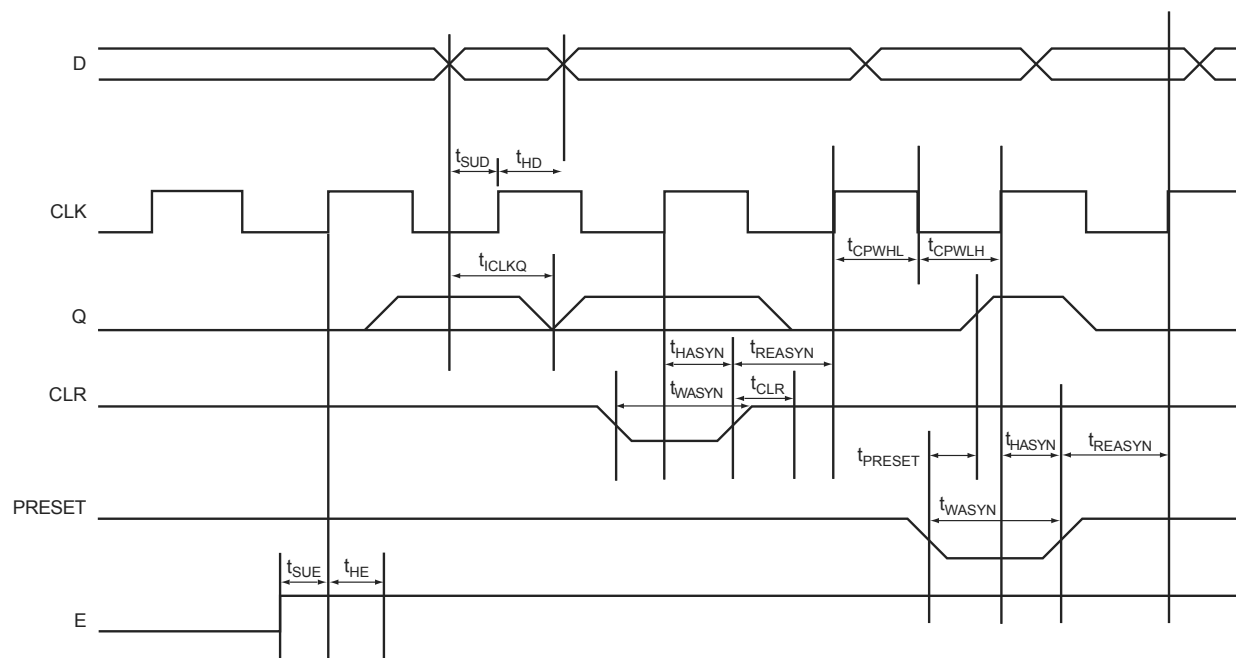


Figure 2-12 • Input Register Timing Characteristics

Table 2-22 • 3.3 V LVTTTL I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVTTTL Output Drive Strength = 2 (12 mA) / Low Slew Rate								
t _{DP}	Input Buffer		1.68		1.92		2.26	ns
t _{PY}	Output Buffer		12.14		13.83		16.26	ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		12.43		14.16		16.65	ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		12.17		13.86		16.30	ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.73		1.74		1.75	ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.22		2.23		2.24	ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.38		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Table 2-22 • 3.3 V LVTTTL I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVTTTL Output Drive Strength =3 (16 mA) / Low Slew Rate								
t _{DP}	Input Buffer		1.68		1.92		2.26	ns
t _{PY}	Output Buffer		11.03		12.56		14.77	ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		11.42		13.01		15.29	ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		11.04		12.58		14.79	ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.86		1.88		1.88	ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.50		2.51		2.52	ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Table 2-22 • 3.3 V LVTTTL I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVTTTL Output Drive Strength =3 (16 mA) / High Slew Rate								
t _{DP}	Input Buffer		1.68		1.92		2.26	ns
t _{PY}	Output Buffer		3.12		3.56		4.18	ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.54		4.04		4.75	ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		2.78		3.17		3.72	ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.91		1.93		1.93	ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.58		2.59		2.60	ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

3.3 V PCI, 3.3 V PCI-X

Peripheral Component Interface for 3.3 V standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses an LVTTTL input buffer and a push-pull output buffer. The input and output buffers are 5 V tolerant with the aid of external components. Axcelerator 3.3 V PCI and 3.3 V PCI-X buffers are compliant with the PCI Local Bus Specification Rev. 2.1.

The PCI Compliance Specification requires the clamp diodes to be able to withstand for 11 ns, -3.5 V in undershoot, and 7.1 V in overshoot.

Table 2-33 • DC Input and Output Levels

	VIL		VIH		VOL	VOH	IOL	IOH
	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
PCI	-0.3	0.3 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			
PCI-X	-0.5	0.35 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			

AC Loadings

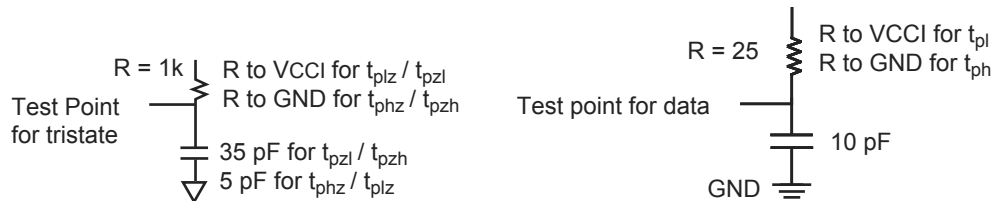


Figure 2-18 • AC Test Loads

Table 2-34 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C _{load} (pF)
(Per PCI Spec and PCI-X Spec)			N/A	10

Note: * Measuring Point = VTRIP

Table 2-77 • AX500 Routed Array Clock Networks

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
Routed Array Clock Networks								
t _{RCKL}	Input Low to High		2.31		2.63		3.09	ns
t _{RCKH}	Input High to Low		2.44		2.78		3.27	ns
t _{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t _{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t _{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t _{RP}	Minimum Period	1.15		1.31		1.54		ns
t _{RMAX}	Maximum Frequency		870		763		649	MHz

Table 2-78 • AX1000 Routed Array Clock Networks

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
Routed Array Clock Networks								
t _{RCKL}	Input Low to High		3.08		3.50		4.12	ns
t _{RCKH}	Input High to Low		3.13		3.56		4.19	ns
t _{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t _{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t _{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t _{RP}	Minimum Period	1.15		1.31		1.54		ns
t _{RMAX}	Maximum Frequency		870		763		649	MHz

Table 2-79 • AX2000 Routed Array Clock Networks

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
Routed Array Clock Networks								
t _{RCKL}	Input Low to High		3.08		3.50		4.12	ns
t _{RCKH}	Input High to Low		3.13		3.56		4.19	ns
t _{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t _{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t _{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t _{RP}	Minimum Period	1.15		1.31		1.54		ns
t _{RMAX}	Maximum Frequency		870		763		649	MHz

The ClockTileDist Cluster contains an HCLKMux (HM) module for each of the four HCLK trees and a CLKMux (CM) module for each of the CLK trees. The HCLK branches then propagate horizontally through the middle of the core tile to HCLKColDist (HD) modules in every SuperCluster column. The CLK branches propagate vertically through the center of the core tile to CLKRowDist (RD) modules in every SuperCluster row. Together, the HCLK and CLK branches provide for a low-skew global fanout within the core tile (Figure 2-40 and Figure 2-41).

Figure 2-40 • CTD, CD, and HD Module Layout

Figure 2-41 • HCLK and CLK Distribution within a Core Tile

CLK1 and CLK2

Both PLL outputs, CLK1 and CLK2, can be used to drive a global resource, an adjacent PLL RefCLK input, or a net in the FPGA core. Not all drive combinations are possible (Table 2-81).

Table 2-81 • PLL General Connections Rules

CLK1	CLK2
HCLK	HCLK
CLK	CLK
HCLK	Routed net output
Routed net output	HCLK
HCLK	NONE
NONE	HCLK
CLK	NONE
NONE	CLK

Note: The PLL outputs remain Low when REFCLK is constant (either Low or High).

Restrictions on CLK1 and CLK2

- When both are driving global resources, they must be driving the same type of global resource (i.e. either HCLK or CLK).
- Only one can drive a routed net at any given time.

Table 2-82 and Table 2-83 specify all the possible CLK1 and CLK2 connections for the north and south PLLs. HCLK1 and HCLK2 are used to denote the different HCLK networks when two are being driven at the same time by a single PLL (Note that HCLK1 is the primary clock resource associated with the PLL, and HCLK2 is the clock resource associated with the adjacent PLL). Likewise, CLK1 and CLK2 are used to denote the different CLK networks when two are being driven at the same time by a single PLL (Figure 2-48 on page 2-75).

Table 2-82 • North PLL Connections

CLK1	CLK2
HCLK1	Routed net
HCLK1	Unused
HCLK2	HCLK1
HCLK2	Routed net
HCLK2	Both HCLK1 and routed net
HCLK2	Unused
Unused	HCLK1
Unused	Routed net
Unused	Both HCLK1 and routed net
Unused	Unused
Routed net	HCLK1
Routed net	Unused
Both HCLK1 and HCLK2	Routed net
Both HCLK1 and HCLK2	Unused
Both HCLK1 and routed net	Unusable
Both HCLK2 and routed net	HCLK1
Both HCLK2 and routed net	Unused
HCLK1, HCLK2, and routed net	Unusable

Note: Designer software currently does not support all of these connections. Only exclusive connections where one output connects to a single net are supported at this time (e.g. CLK1 driving HCLK1, and HCLK2 is not supported).

Clock Skew Minimization

Figure 2-56 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the input clock. The input clock is fed to the reference clock input of the PLL. The output clock (CLK2) feeds a routed clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to the *Axcelerator Family PLL and Clock Management* application note for more information.

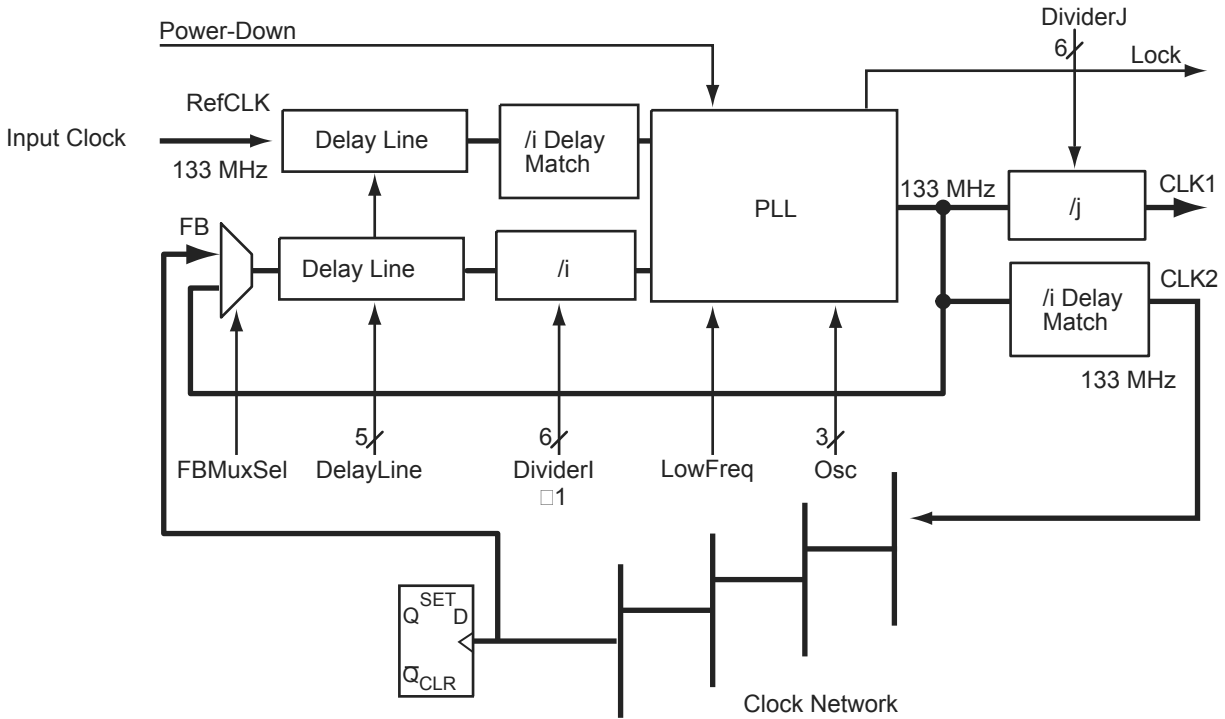


Figure 2-56 • Using the PLL for Clock Deskewing

Figure 2-63 illustrates flag generation.

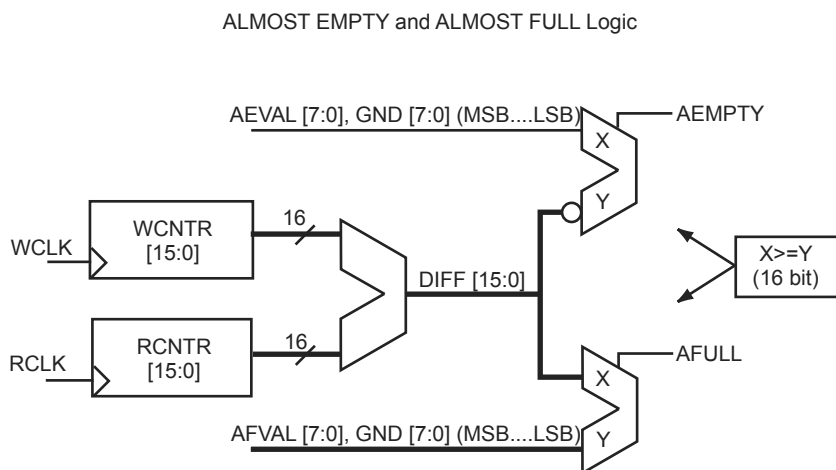


Figure 2-63 • ALMOST-EMPTY and ALMOST-FULL Logic

The Verilog codes for the flags are:

```
assign AF = (DIFF[15:0] >= {AFVAL[7:0], 8'b00000000})?1:0;
assign AE = ({AEVAL[7:0], 8'b00000000} >= DIFF[15:0])?1:0;
```

The number of DIFF-bits active depends on the configuration depth and width (Table 2-95).

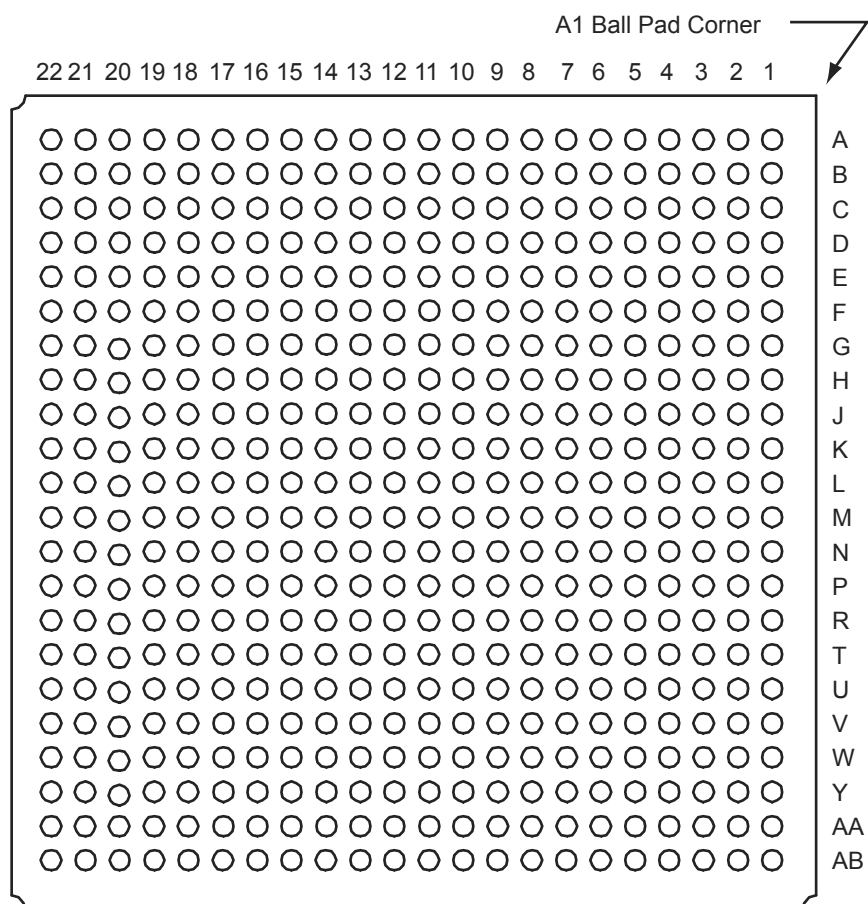
Table 2-95 • Number of Available Configuration Bits

Number of Blocks	Block DxW	Number of AEVAL/AFVAL Bits
1	1x1	4
2	1x2	4
2	2x1	5
4	1x4	4
4	2x2	5
4	4x1	6
8	1x8	4
8	2x4	5
8	4x2	6
8	8x1	7
16	1x16	4
16	2x8	5
16	4x4	6
16	8x2	7
16	16x1	8

The active-high CLR pin is used to reset the FIFO to the empty state, which sets FULL and AFULL low, and EMPTY and AEMPTY high.

Assuming that the EMPTY flag is not set, new data is read from the FIFO when REN is valid on the active edge of the clock. Write and read transfers are described with timing requirements in "Timing Characteristics" on page 2-100.

FG484



Note

For Package Manufacturing and Environmental information, visit Resource center at <http://www.microsemi.com/soc/products/rescenter/package/index.html>.

FG896	
AX2000 Function	Pin Number
Bank 0	
IO00NB0F0	B4
IO00PB0F0	A4
IO01NB0F0	F8
IO01PB0F0	F7
IO02NB0F0	D6
IO02PB0F0	E6
IO04NB0F0	A5
IO04PB0F0	B5
IO05NB0F0	H8
IO05PB0F0	G8
IO06NB0F0	D7
IO06PB0F0	E7
IO07NB0F0	D8
IO07PB0F0	E8
IO08NB0F0	C7
IO08PB0F0	C6
IO09NB0F0	G9
IO09PB0F0	H9
IO10NB0F0	A6
IO10PB0F0	B6
IO11NB0F0	H10
IO11PB0F0	G10
IO12NB0F1	E9
IO12PB0F1	F9
IO13NB0F1	E10
IO13PB0F1	F10
IO15NB0F1	F11
IO15PB0F1	G11
IO16NB0F1	A7
IO16PB0F1	B7
IO17NB0F1	D10
IO17PB0F1	D9
IO18NB0F1	C9
IO18PB0F1	C8

FG896	
AX2000 Function	Pin Number
IO19NB0F1	D11
IO19PB0F1	E11
IO20PB0F1	B8
IO21NB0F1	H12
IO21PB0F1	H11
IO23NB0F2	A10
IO23PB0F2	A9
IO25NB0F2	F12
IO25PB0F2	G12
IO26NB0F2	B11
IO26PB0F2	B10
IO27NB0F2	D12
IO27PB0F2	E12
IO28NB0F2	C12
IO28PB0F2	C11
IO30NB0F2	A12
IO30PB0F2	A11
IO31NB0F2	F13
IO31PB0F2	G13
IO33NB0F2	H13
IO33PB0F2	J13
IO34NB0F3	B13
IO34PB0F3	B12
IO37NB0F3	E14
IO37PB0F3	E13
IO38NB0F3	B14
IO38PB0F3	A14
IO39NB0F3	H14
IO39PB0F3	J14
IO40NB0F3	B15
IO40PB0F3	A15
IO41NB0F3/HCLKAN	C14
IO41PB0F3/HCLKAP	D14
IO42NB0F3/HCLKBN	E15
IO42PB0F3/HCLKBP	D15

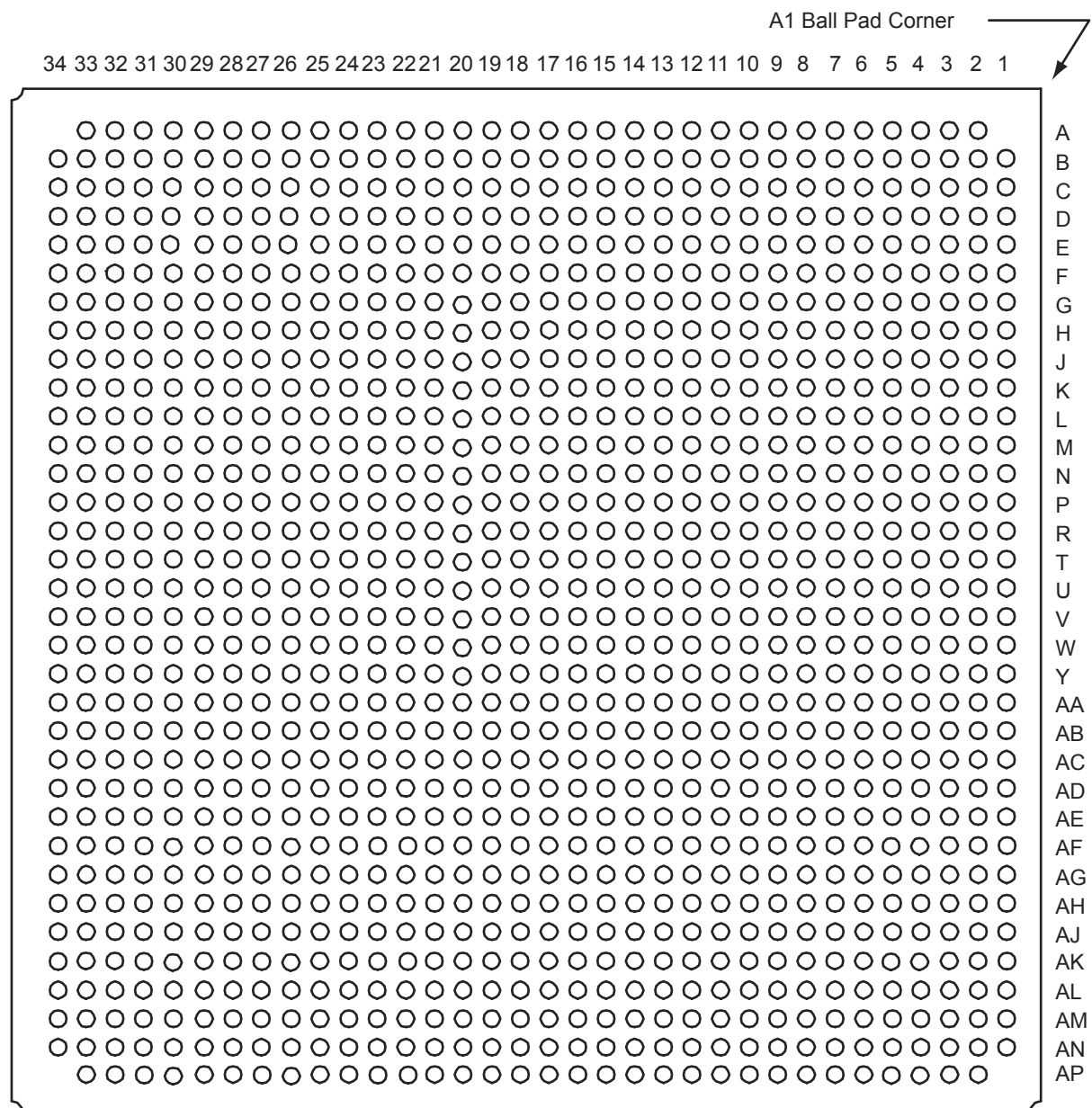
FG896	
AX2000 Function	Pin Number
Bank 1	
IO43NB1F4/HCLKCN	E17
IO43PB1F4/HCLKCP	E16
IO44NB1F4/HCLKDN	C17
IO44PB1F4/HCLKDP	D17
IO45NB1F4	A16
IO45PB1F4	B16
IO47NB1F4	H17
IO47PB1F4	J17
IO48NB1F4	A17
IO48PB1F4	B17
IO49NB1F4	H18
IO49PB1F4	J18
IO51NB1F4	F18
IO51PB1F4	G18
IO52NB1F4	B18
IO53NB1F4	D18
IO53PB1F4	C18
IO55NB1F5	H19
IO55PB1F5	G19
IO56NB1F5	B19
IO56PB1F5	A19
IO57NB1F5	E20
IO57PB1F5	E19
IO58NB1F5	C20
IO58PB1F5	C19
IO59NB1F5	B20
IO59PB1F5	A20
IO61NB1F5	F20
IO61PB1F5	F19
IO62NB1F5	A22
IO62PB1F5	A21
IO63NB1F5	D21
IO63PB1F5	D20
IO65NB1F6	G20

FG896	
AX2000 Function	Pin Number
GND	AK18
GND	AK2
GND	AK23
GND	AK29
GND	AK8
GND	B1
GND	B2
GND	B22
GND	B29
GND	B30
GND	B9
GND	C10
GND	C15
GND	C16
GND	C21
GND	C28
GND	C3
GND	D27
GND	D28
GND	D4
GND	E26
GND	E5
GND	H1
GND	H30
GND	J2
GND	J22
GND	J29
GND	J9
GND	K10
GND	K21
GND	K28
GND	K3
GND	L11
GND	L20
GND	M12

FG896	
AX2000 Function	Pin Number
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	M18
GND	M19
GND	N1
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N18
GND	N19
GND	N30
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P18
GND	P19
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	R18
GND	R19
GND	R28
GND	R3

FG896	
AX2000 Function	Pin Number
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	T18
GND	T19
GND	T28
GND	T3
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	U18
GND	U19
GND	V1
GND	V12
GND	V13
GND	V14
GND	V15
GND	V16
GND	V17
GND	V18
GND	V19
GND	V30
GND	W12
GND	W13
GND	W14
GND	W15
GND	W16
GND	W17
GND	W18

FG1152



Note

For Package Manufacturing and Environmental information, visit Resource center at <http://www.microsemi.com/soc/products/rescenter/package/index.html>.

CQ208	
AX250 Function	Pin Number
IO110PB7F7	19
IO112NB7F7	16
IO112PB7F7	17
IO117NB7F7	12
IO117PB7F7	13
IO119NB7F7	10
IO119PB7F7	11
IO121PB7F7	7
IO122NB7F7	5
IO122PB7F7	6
IO123NB7F7	3
IO123PB7F7	4
Dedicated I/O	
GND	9
GND	15
GND	21
GND	32
GND	39
GND	46
GND	51
GND	59
GND	65
GND	69
GND	90
GND	94
GND	99
GND	104
GND	113
GND	119
GND	125
GND	136
GND	143
GND	150
GND	155
GND	164
GND	169
GND	173

CQ208	
AX250 Function	Pin Number
GND	194
GND	196
GND	201
GND/LP	208
PRA	184
PRB	183
PRC	80
PRD	79
TCK	205
TDI	204
TDO	203
TMS	206
TRST	207
VCCA	2
VCCA	14
VCCA	38
VCCA	52
VCCA	64
VCCA	93
VCCA	118
VCCA	142
VCCA	156
VCCA	168
VCCA	195
VCCDA	1
VCCDA	26
VCCDA	53
VCCDA	63
VCCDA	78
VCCDA	95
VCCDA	105
VCCDA	130
VCCDA	157
VCCDA	167
VCCDA	182
VCCDA	202
VCCIB0	193

CQ208	
AX250 Function	Pin Number
VCCIB0	200
VCCIB1	163
VCCIB1	172
VCCIB2	135
VCCIB2	149
VCCIB3	112
VCCIB3	124
VCCIB4	89
VCCIB4	98
VCCIB5	58
VCCIB5	68
VCCIB6	31
VCCIB6	45
VCCIB7	8
VCCIB7	20
VCCPLA	189
VCCPLB	187
VCCPLC	178
VCCPLD	176
VCCPLE	85
VCCPLF	83
VCCPLG	74
VCCPLH	72
VCOMPLA	190
VCOMPLB	188
VCOMPLC	179
VCOMPLD	177
VCOMPLE	86
VCOMPLF	84
VCOMPLG	75
VCOMPLH	73
VPUMP	158

CQ256	
AX2000 Function	Pin Number
Bank 0	
IO01NB0F0	248
IO01PB0F0	249
IO04NB0F0	246
IO04PB0F0	247
IO05NB0F0	242
IO05PB0F0	243
IO08NB0F0	240
IO08PB0F0	241
Bank 0	
IO37NB0F3	234
IO37PB0F3	235
IO41NB0F3/HCLKAN	232
IO41PB0F3/HCLKAP	233
IO42NB0F3/HCLKBN	228
IO42PB0F3/HCLKBP	229
Bank 1 -	
IO43NB1F4/HCLKCN	220
IO43PB1F4/HCLKCP	221
IO44NB1F4/HCLKDN	216
IO44PB1F4/HCLKDP	217
Bank 1	
IO65NB1F6	210
IO65PB1F6	211
IO69NB1F6	208
IO69PB1F6	209
IO70NB1F6	199
IO71NB1F6	204
IO71PB1F6	205
IO73NB1F6	202
IO73PB1F6	203
IO74NB1F6	197
IO74PB1F6	198
Bank 2	
IO87NB2F8	187

CQ256	
AX2000 Function	Pin Number
IO87PB2F8	188
IO89PB2F8	186
Bank 2	
IO107NB2F10	184
IO107PB2F10	185
IO110NB2F10	180
IO110PB2F10	181
IO111NB2F10	178
IO111PB2F10	179
IO112NB2F10	174
IO112PB2F10	175
IO113NB2F10	172
IO113PB2F10	173
IO114NB2F10	168
IO114PB2F10	169
IO115NB2F10	166
IO115PB2F10	167
IO117NB2F10	162
IO117PB2F10	163
Bank 3	
IO139NB3F13	158
IO139PB3F13	159
IO141NB3F13	154
IO141PB3F13	155
IO142NB3F13	152
IO142PB3F13	153
IO145NB3F13	148
IO145PB3F13	149
IO146NB3F13	146
IO146PB3F13	147
IO147NB3F13	140
IO147PB3F13	141
IO148NB3F13	142
IO148PB3F13	143
IO149NB3F13	136

CQ256	
AX2000 Function	Pin Number
IO149PB3F13	137
Bank 3	
IO165NB3F15	135
IO167NB3F15	133
IO167PB3F15	134
Bank 4	
IO181NB4F17	124
IO181PB4F17	125
IO182NB4F17	122
IO182PB4F17	123
IO183NB4F17	118
IO183PB4F17	119
IO184NB4F17	116
IO184PB4F17	117
IO190NB4F17	112
IO190PB4F17	113
IO192NB4F17	110
IO192PB4F17	111
Bank 4	
IO212NB4F19/CLKEN	104
IO212PB4F19/CLKEP	105
IO213NB4F19/CLKFN	100
IO213PB4F19/CLKFP	101
Bank 5	
IO214NB5F20/CLKGN	92
IO214PB5F20/CLKGP	93
IO215NB5F20/CLKHN	88
IO215PB5F20/CLKHP	89
Bank 5	
IO236NB5F22	82
IO236PB5F22	83
IO238NB5F22	80
IO238PB5F22	81
IO240NB5F22	76
IO240PB5F22	77

CG624	
AX2000 Function	Pin Number
IO157PB3F14	U20
IO158NB3F14	AB25
IO158PB3F14	AA25
IO160PB3F14	W24
IO161NB3F15	U24
IO161PB3F15	U23
IO162NB3F15	AA24
IO162PB3F15	Y24
IO163NB3F15	V22
IO163PB3F15	U22
IO164NB3F15	V23
IO164PB3F15	V24
IO166NB3F15	AB24
IO167NB3F15	V21
IO167PB3F15	U21
IO168NB3F15	Y23
IO168PB3F15	AA23
IO169NB3F15	W22*
IO169PB3F15	W23*
IO170NB3F15	Y22
IO170PB3F15	Y21
Bank 4	
IO171NB4F16	AC20*
IO171PB4F16	AC21*
IO172NB4F16	W20
IO172PB4F16	Y20
IO173NB4F16	AD21
IO173PB4F16	AD22
IO174NB4F16	AA19
IO176NB4F16	Y18
IO176PB4F16	Y19
IO177NB4F16	AB19

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO177PB4F16	AB18
IO182NB4F17	V19
IO182PB4F17	W19
IO183PB4F17	AC19
IO184NB4F17	AB17
IO184PB4F17	AC17
IO185NB4F17	AD19
IO185PB4F17	AD20
IO187PB4F17	AC18
IO188NB4F17	Y17
IO188PB4F17	AA17
IO189PB4F17	AE22
IO191NB4F17	W18
IO191PB4F17	V18
IO192PB4F17	U18
IO195PB4F18	AE21
IO196NB4F18	AB16
IO197NB4F18	AD17
IO197PB4F18	AD18
IO198NB4F18	V17
IO198PB4F18	W17
IO199NB4F18	AE19
IO199PB4F18	AE20
IO200NB4F18	AC15
IO201NB4F18	AD15
IO201PB4F18	AD16
IO202NB4F18	Y15
IO202PB4F18	Y16
IO206NB4F19	AB14
IO206PB4F19	AB15
IO207NB4F19	AE15
IO207PB4F19	AE16

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO208PB4F19	W16
IO209NB4F19	AE14
IO210NB4F19	V15
IO210PB4F19	V16
IO211NB4F19	AD14
IO211PB4F19	AC14
IO212NB4F19/CLKEN	W14
IO212PB4F19/CLKEP	W15
IO213NB4F19/CLKFN	AC13
IO213PB4F19/CLKFP	AD13
Bank 5	
IO214NB5F20/CLKGN	W13
IO214PB5F20/CLKGP	Y13
IO215NB5F20/CLKHN	AC12
IO215PB5F20/CLKHP	AD12
IO216NB5F20	U13
IO216PB5F20	V13
IO217NB5F20	AE10
IO217PB5F20	AE11
IO218NB5F20	W11
IO218PB5F20	W12
IO222NB5F20	AA11
IO222PB5F20	Y11
IO223PB5F21	AE9
IO225NB5F21	AE6
IO225PB5F21	AE7
IO226NB5F21	Y10
IO226PB5F21	W10
IO227PB5F21	T13
IO228NB5F21	AB10
IO228PB5F21	AB11
IO229NB5F21	AD9

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

4 – Datasheet Information

List of Changes

The following table lists critical changes that were made in the current version of the document.

Revision	Changes	Page
Revision 18 (March 2012)	Table 2-1 • Absolute Maximum Ratings was updated to correct the maximum DC core supply voltage (VCCA) from 1.6 V to 1.7 V (SAR 36786). The maximum input voltage (VI) was corrected from 3.75 V to 4.1 V (SAR 35419).	2-1
	Values for tristate leakage current IOZ, and I _{IH} and I _{IL} were added to Table 2-3 • Standby Current (SARs 35774, 32021).	2-2
	Figure 2-2 • VCCPLX and VCOMPLX Power Supply Connect was updated to correct the units for the resistance from "W" to Ω (SAR 36415).	2-9
	In the Introduction to the "User I/Os" section, the following sentence was added to clarify the slew rate setting (SAR 34943): The slew rate setting is effective for both rising and falling edges.	2-11
	Figure 2-3 • Use of an External Resistor for 5 V Tolerance was revised to show the VCCI and GND clamp diodes. The explanatory text above the figure was revised as well (SAR 34942).	2-13
	EQ 3 for 5 V tolerance was corrected to change V _{diode} from 0.6 V to 0.7 V (SAR 36786).	2-13
	Additional information was added to the "Using the Weak Pull-Up and Pull-Down Circuits" section to clarify how the weak pull-up and pull-down resistors are physically implemented (SAR 34945).	2-17
	The description for the C _{INCLK} parameter in Table 2-18 • Input Capacitance was changed from "Input capacitance on clock pin" to "Input capacitance on HCLK and RCLK pin" (SAR 34944).	2-21
	Table 2-19 • I/O Input Rise Time and Fall Time* is new (SAR 34942).	2-21
	The minimum V _{IL} for 1.5 V LVCMOS and PCI was corrected from –0.5 to –0.3 in Table 2-29 • DC Input and Output Levels and Table 2-33 • DC Input and Output Levels (SAR 34358).	2-38, 2-40
	Support for simulating the GCLR/ GPSET feature in the Axcelerator Family was added in Libero software v9.0 SPI1. Reference to the section explaining this in the <i>Antifuse Macro Library Guide</i> was added to the "R-Cell" section (SAR 26413).	2-58
Revision 17 (September 2011)	The enable signal in Figure 2-32 • R-Cell Delays was corrected to show it is active low rather than active high (SAR 34946).	2-59
	The versioning system for datasheets has been changed. Datasheets are assigned a revision number that increments each time the datasheet is revised. The "Axcelerator Family Device Status" table indicates the status for each device in the device family.	iii
	The "Features" section, "Programmable Interconnect Element" section, and "Security" section were revised to clarify that although no existing security measures can give an absolute guarantee, Microsemi FPGAs implement the best security available in the industry (SAR 32865).	i, 1-1, 2-108



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